How energy efficiency is driving the future of computing



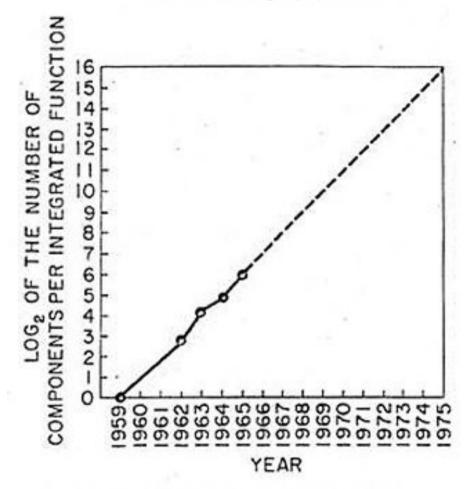
Simon McIntosh-Smith University of Bristol, UK simon@cs.bris.ac.uk





Ke The real Moore's Law

Moore's Law graph, 1965



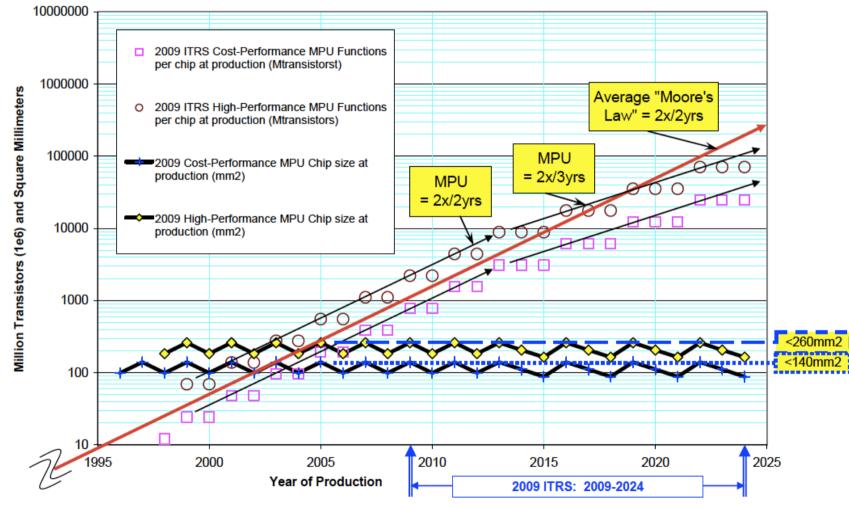
45 years ago, Gordon Moore observed that the number of transistors on a single chip was doubling rapidly

Fig. 2 Number of components per Integrated function for minimum cost per component extrapolated vs time.



Ke Moore's Law today

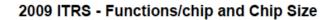
2009 ITRS - Functions/chip and Chip Size

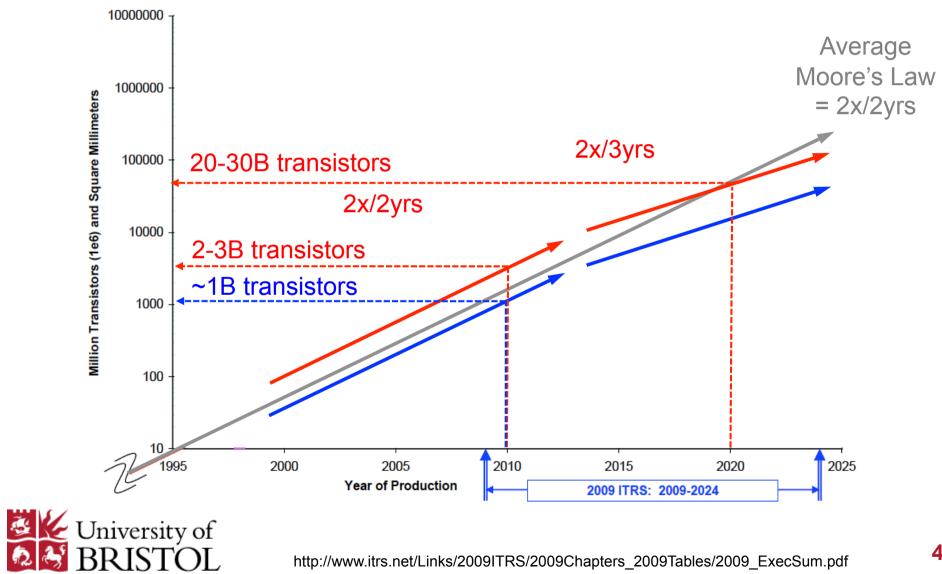




http://www.itrs.net/Links/2009ITRS/2009Chapters_2009Tables/2009_ExecSum.pdf

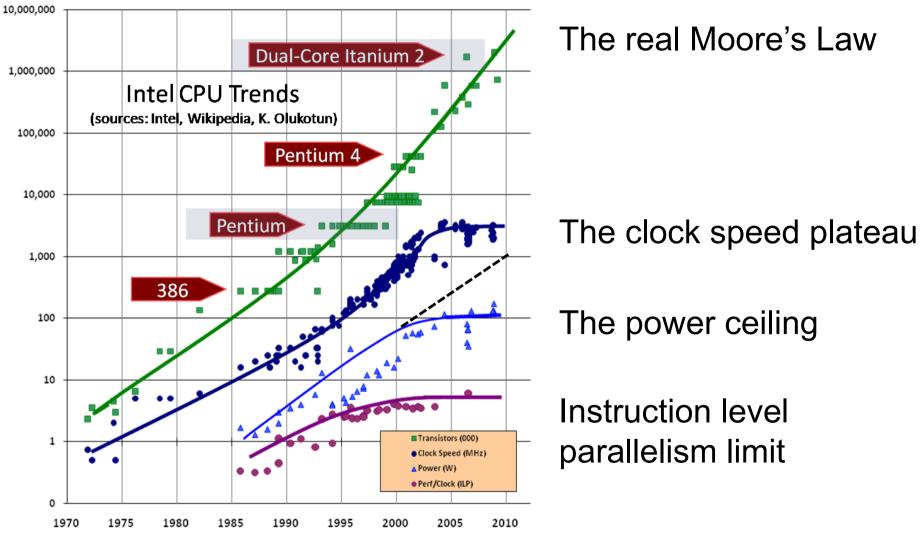
Ke Moore's Law today





http://www.itrs.net/Links/2009ITRS/2009Chapters_2009Tables/2009_ExecSum.pdf

Important technology trends





Herb Sutter, "The free lunch is over", Dr. Dobb's Journal, 30(3), March 2005. On-line version, August 2009. http://www.gotw.ca/publications/concurrency-ddj.htm

Power-limited regimes

- Processor power consumption now has an upper bound which may even reduce over time
- Power consumption ∞
 - Clock frequency
 - Number of transistors (chip area)
 Number of cores
 - Voltage²
- When power has an upper bound, "performance per watt = performance"



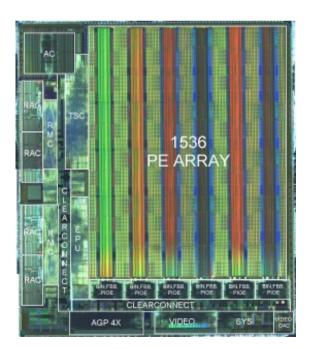
What to do with billions of transistors?

- Lots more cores on-chip
 - Core designs will stay roughly the same or get simpler
- Power consumption has to be held in check
 - Chip voltages *can't be dialled down any more* (0.7V)
 - Clock speeds will tend to decrease
 - Memory bandwidth per core will tend to decrease
 - Memory per core will tend to decrease
 - The DARK SILICON challenge
- Different types of cores
 - Heterogeneous computing
 - E.g. a few heavyweight (x86) cores together with lots of lightweight (GPU) cores
 - Likely to go the same way as vector units, i.e. mainstream



Future processor architectures

- Hundreds or thousands of cores per chip
- Lower clock speeds
- Highly integrated (mainstream)



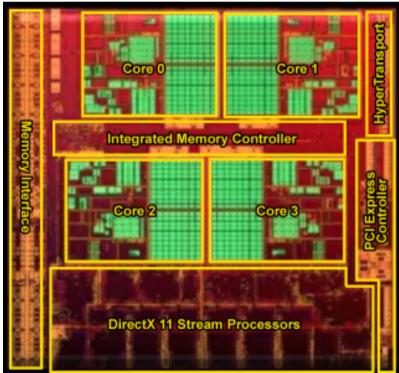
Pixelfusion F150 1,536 simple PEs 200MHz Circa 2000



Ke The future is now...

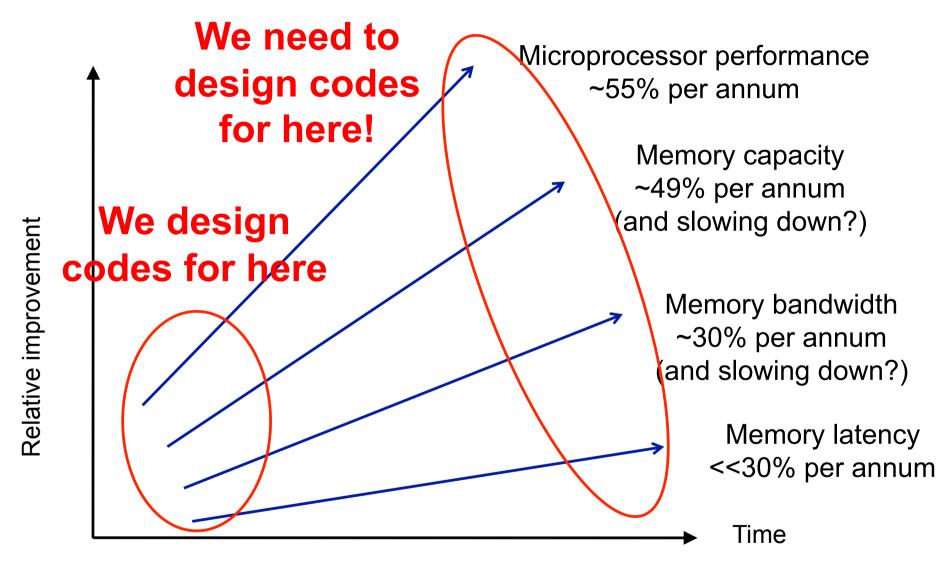
AMD's first "Fusion" chip, disclosed at ISSCC in San Francisco, Feb 2010

- 'Llano' Accelerated Processing Unit (APU)
- Integrates a quad core x86 CPU with an OpenCL programmable GPU in the same chip
- Also Intel, Nvidia, IBM...





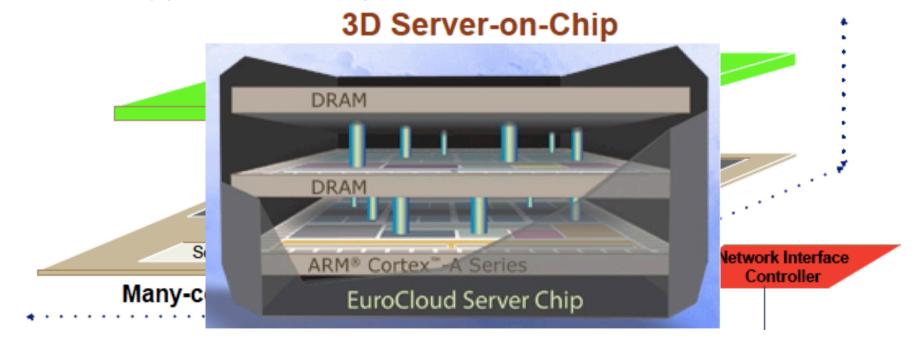
KRelative hardware trends





✓ 3D stacked memories

 Vertically stack many-core processors with DRAM → greater bandwidth and greater energy efficiency

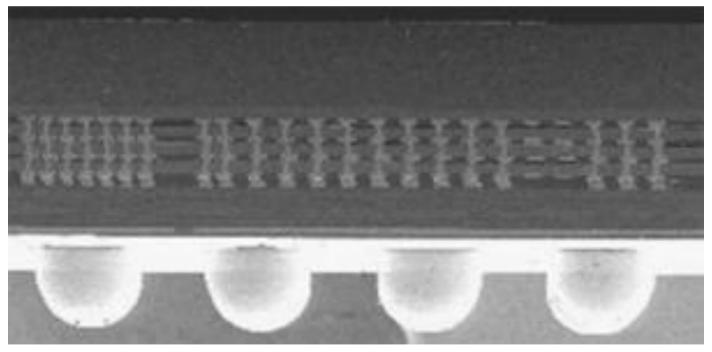




Eurocloud FP7 project, <u>www.eurocloudserver.com</u> 11

✓ 3D stacked memories

 Vertically stack many-core processors with DRAM → greater bandwidth and greater energy efficiency





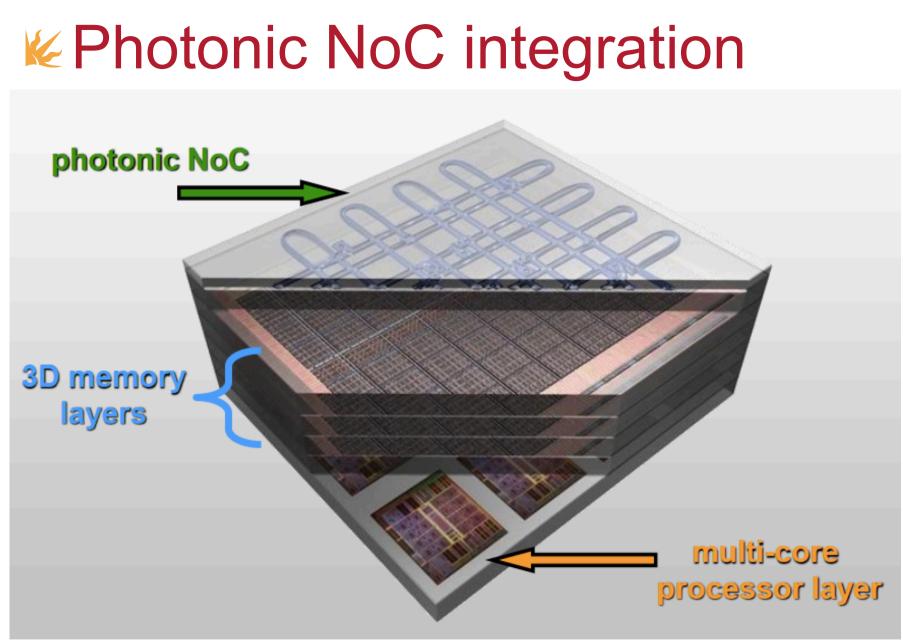
Samsung 3D DRAM

Photonic networks

- Roadmaps to achieve ExaFLOPs (10¹⁸) by 2018 are relying on some major hardware breakthroughs to improve energy efficiency
- Prof Keren Bergmen's work at Columbia sponsored by US DoE, Intel, IBM
- Moving data becoming an increasingly dominant fraction of energy dissipation in microelectronics

> "Compute free, bandwidth expensive"







Bergmen, SIAM PP10, Feb 2010

Control of the supercomputing board

CMPs 3DI Stack

Silicon Photonic Interconnection Network

Memory Stack

CMPs

Supercomputing board with CMPs 3DI stack and DRAM

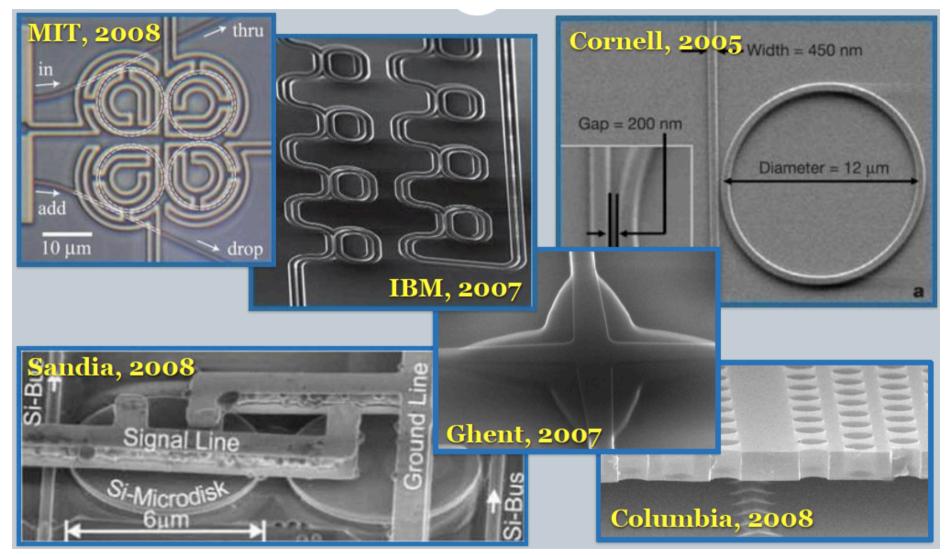
DRAM

10 teraflops per chip 64 CMPs per chip 3DI stack with CMPs, memory, and photonic NoC

Bisectional data rate on-chip: 10 TB/s Bisectional data rate off-chip: 10 TB/s University of BRISTOL Bergmen, SIAM **Potential disruption!**

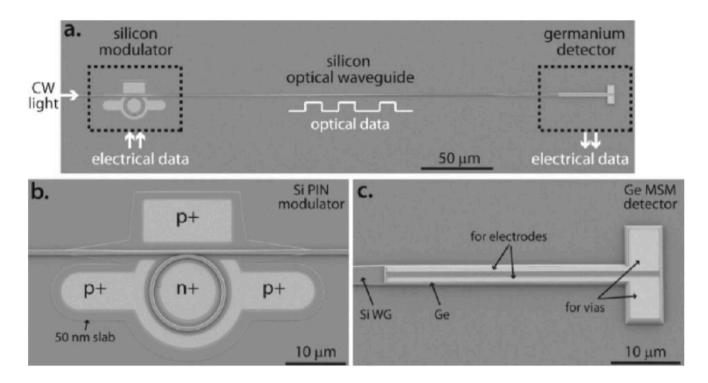
Bergmen, SIAM PP10, Feb 2010

KSilicon photonic integration





First complete photonic link

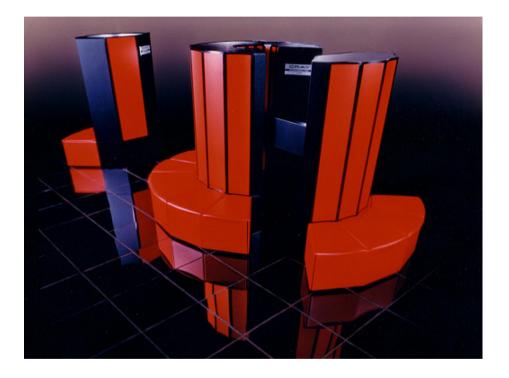


Integrated optical interconnect with silicon electro-optical modulator, silicon waveguide, and germanium-on-silicon photodetector

L. Chen, Optics Express, August 2009



We Does anyone else care about energy efficiency?



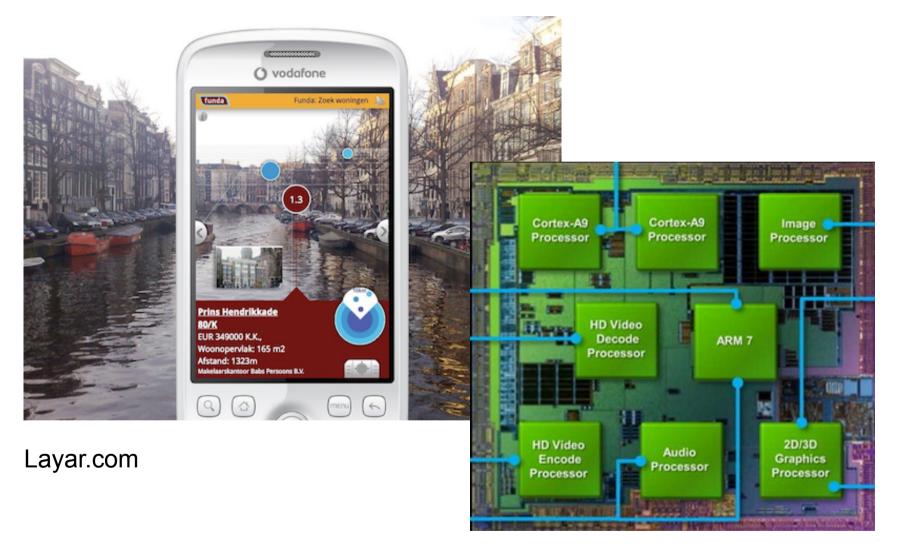


Cray X-MP, mid 1980's

Apple iPhone, 2007



Mobile augmented reality





Nvidia Tegra 2

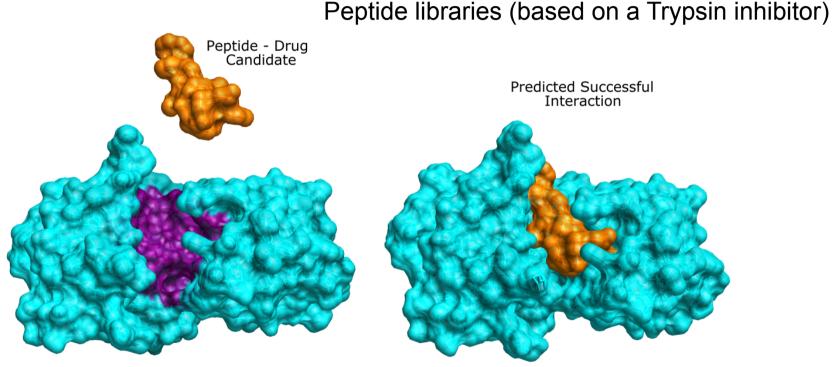
Power efficiency in software

- It's not just hardware that can affect energy efficiency:
 - Moving data uses more energy than processing it
 - Bloated software uses more energy while sitting in dynamic memories (DRAMs)
 - It may be possible to improve performance per watt by 10-20% purely through changes to software optimisation



Kernistol drug docking example

Therapy for Emphysema

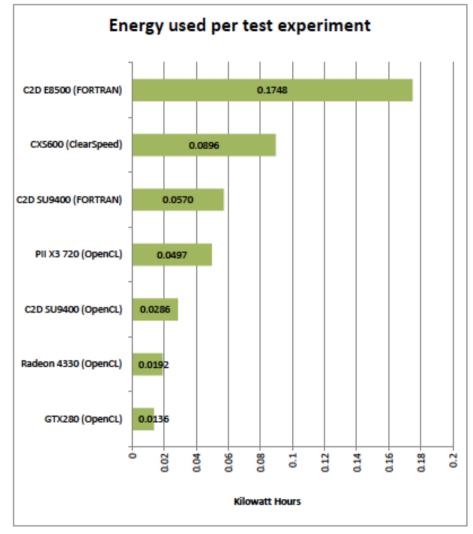


Enzyme - Drug Target

Flexible amino acid side-chains in both protein (receptor) and ligand (peptide)



KegpUs show energy efficiency



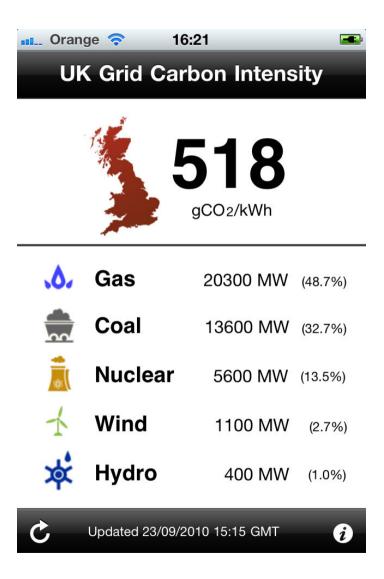
Dual core x86 CPU



AMD GPU Nvidia C2050 GPU

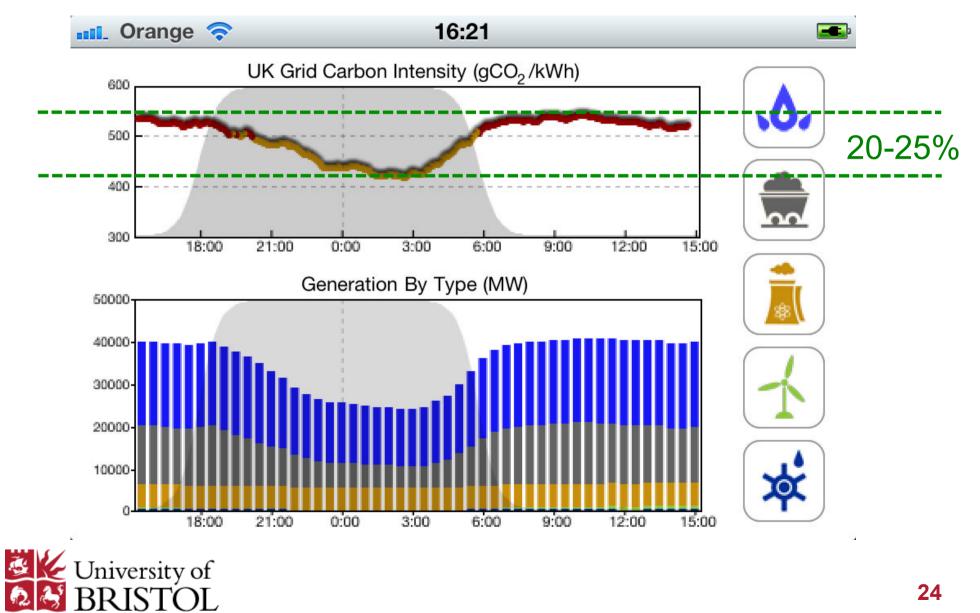


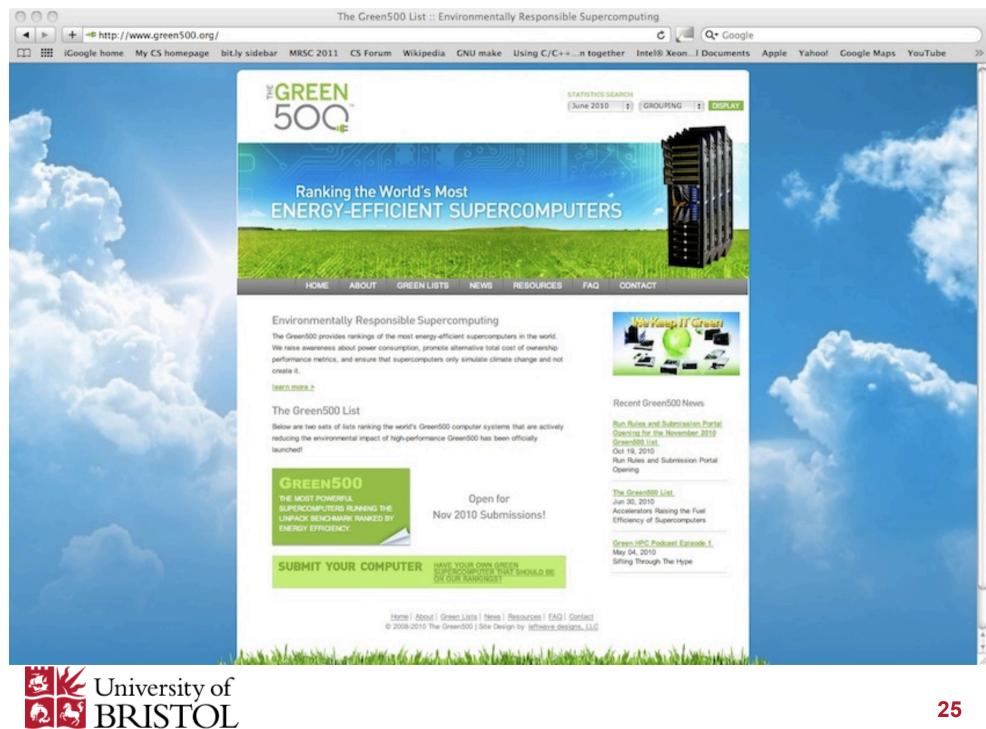
12.8X difference between best and worst





We Optimising carbon emissions





KGreen 500

| Green500 Rank | MFLOPS/W | Site* | Computer* | Total Power (kW) |
|------------------|----------|--|---|------------------------|
| 1 | 773.38 | Forschungszentrum Juelich (FZJ) | QPACE SFB TR Cluster, PowerXCell 8i, 3.2 GHz, 3D- Torus | 57.54 |
| 1 | 773.38 | Universitaet Regensburg | QPACE SFB TR Cluster, PowerXCell 8i, 3.2 GHz, 3D- Torus | 57.54 |
| 1 | 773.38 | Universitaet Wuppertal | QPACE SFB TR Cluster, PowerXCell 8i, 3.2 GHz, 3D- Torus | 57.54 |
| 4 | 492.64 | National Supercomputing Centre in Shenzhen (NSCS) | Dawning Nebulae, TC3600 blade CB60-G2 cluster, Intel Xeon 5650/ nVidia C2050, Infiniband | 2580 |
| 5 | 458.33 | DOE/NNSA/LANL | BladeCenter QS22/LS21 Cluster, PowerXCell 8i 3.2 Ghz / Opteron DC 1.8 GHz, Infiniband | 276 |
| 5 | 458.33 | IBM Poughkeepsie Benchmarking Center | BladeCenter QS22/LS21 Cluster, PowerXCell 8i 3.2 Ghz / Opteron DC 1.8 GHz, Infiniband | 138 |
| 7 | 444.25 | DOE/NNSA/LANL | BladeCenter QS22/LS21 Cluster, PowerXCell 8i 3.2 Ghz / Opteron DC 1.8 GHz, Voltaire Infiniband | 2345.5 |
| 8 | 431.88 | Institute of Process Engineering, Chinese Academy of Sciences | Mole-8.5 Cluster Xeon L5520 2.26 Ghz, nVidia Tesla, Infiniband | 480 |
| 9 | 418.47 | Mississippi State University | iDataPlex, Xeon X56xx 6C 2.8 GHz, Infiniband | 72 |
| 10 | 397.56 | Banking (M) | iDataPlex, Xeon X56xx 6C 2.66 GHz, Infiniband | 72 |

* Performance data obtained from publicly available sources including TOP500



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Important takeaways

- Energy efficiency is becoming *the* first order consideration driving performance
- Heterogeneous computing is here to stay
- Even single chips will contain thousands of cores
- Hierarchies will become deeper
 - Processing, interconnect, memory, software
- Parallelism is now increasing exponentially and will continue to do so
- Software developers will have to start optimising their code for energy efficiency...

